

with and electrically connected to said printed circuit board at said top surface [said first integrated circuit package being electrically connected to said top of said circuit board through said side surface terminal of said integrated circuit package].

Claim 22 (previously amended) The process as recited in claim 21 further including the step of electrically and perpendicularly connecting at least two integrated circuit packages to said circuit board.

Claim 23 (currently amended) The process as recited in claim 21 further including the step of disposing a solder ball between said side surface terminal of said integrated circuit package and said top of said circuit board.

Claim 24 (previously amended) The process as recited in claim 21 further including the step of disposing solder columns between said integrated circuit and said top of said circuit board.

Claim 25 (previously amended) The process as recited in claim 21 further including the step of integrally attaching at least three tabs to said circuit board.

Claim 26 (previously amended) The process as recited in claim 21 wherein said integrated circuit package is further defined as being connected in a substantially perpendicular manner to said circuit board.

Claim 27 (previously amended) The process as recited in claim 21 wherein said integrated circuit package is further defined as being connected at an angle between 30 and 90 degrees to said circuit board.